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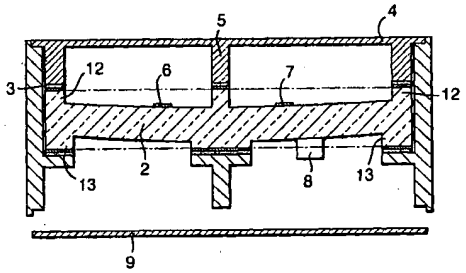
(54) Title: IMPROVEMENTS TO CERAMIC PACKAGES FOR HIGH FREQUENCY CIRCUITS



(57) Abstract: Projecting elongate stub walls (12) and (13) are provided on the planar surfaces of a ceramic substrate (2) at positions where bonding of the substrate to a clamping lid or base is to be carried out. After firing of the substrate, the surfaces (5) thereof are mechanically processed but since the stub walls (12) and (13) protrude from the substrate, the grinding and polishing tools make contact with the surfaces of these stub walls (12) and (13) , rather than with the entire substrate surface. As a result, the area of the substrate to be processed is minimised and problems with dishing and erosion are alleviated. This allows the clamping (10) lid, or frame (4) to be bonded using conventional conductive adhesive (3) processes, avoiding the cracking and stress problems associated with non- uniformity of the surface of the ceramic substrates .

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